



Material Composition Declaration

EPC8009

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.1 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.7393	88.97	91.17	889669
	Silicon oxide	7631-86-9	0.0108	0.35		3496
	Silicon nitride	12033-89-5	0.0033	0.11		1073
	Gallium nitride	25617-97-4	0.0129	0.42		4206
	Aluminum	7429-90-5	0.0188	0.61		6100
	Aluminum nitride	24304-00-5	0.0031	0.10		1010
	Titanium	7440-32-6	0.0005	0.01		149
	Titanium nitride	25583-20-4	0.0017	0.05		544
	Copper	7440-50-8	0.0006	0.02		203
	Tungsten	7440-33-7	0.0002	0.01		56
	Polyimide		0.0160	0.52		5206
Under Bump Metal	Titanium	7440-32-6	0.0004	0.01	1.09	129
	Nickel	7440-02-0	0.0118	0.38		3823
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0213	0.69		6922
Solder Bump	Tin	7440-31-5	0.2324	7.55	7.74	75478
	Silver	7440-22-4	0.0060	0.19		1935
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			3.1	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.